



*Professional in
BGA solder machine*

IR-600 BGA

introduction

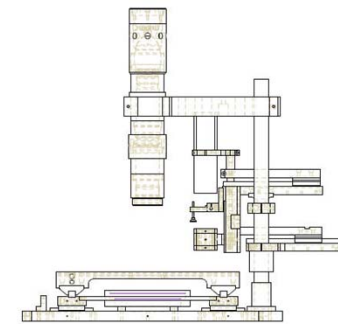
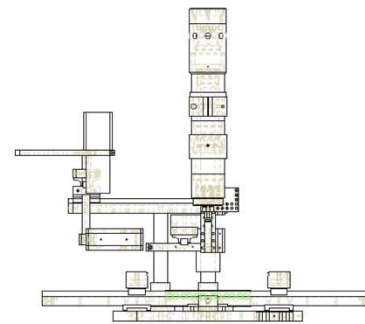
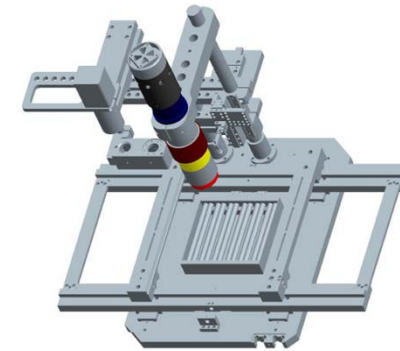
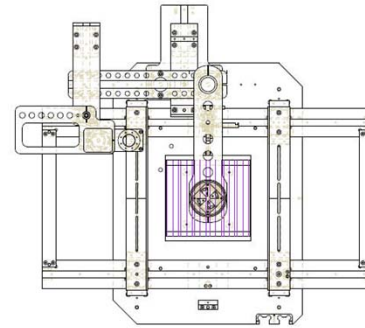
*Editor : Weber Lou
Date : March-12-2011*

IR600 BGA RESOLDER SPEC.

A · Rework System Specifications		
Maximum PCB size	PCB最大尺寸	600 X 500 mm / 24 X 20"
Position accuracy	位移調整精度	±0.02 mm / ±0.00079"
Top power (IR)	上熱最大功率	150 W
Bottom power	下熱最大功率	1,600 W
Temperature setting range	溫度調整範圍	0 - 350 °C / 0 - 660 °F
B · Power Requirements		
Input power requirements	輸入電壓	200 ~ 240 Vac
Single-phase 220 Vac	單相 220 Vac	Neutral / Line / Ground
Required circuit amperage - dedicated line (Fused neutral 15)	需求的安培數 (Fuse 15A)	15 A
Weight	設備總重	60 kg / 133 lbs
Physical dimensions	設備外形長度	W 710 X D 680 X H 650 mm W 28 X D 24 X H 26"
C · Computer System Specifications		
Computer system	PC 系統	Windows® XP
Computer power requirements	PC 電源	120 Vac / 240 Vac
Video display	顯示器	15" TFT LCD display
Video power requirements	顯示器電源	120 Vac / 240 Vac

IR-600 structure

- PC & controller.
- 15" LCD monitor.
- IR-600 mechanic.

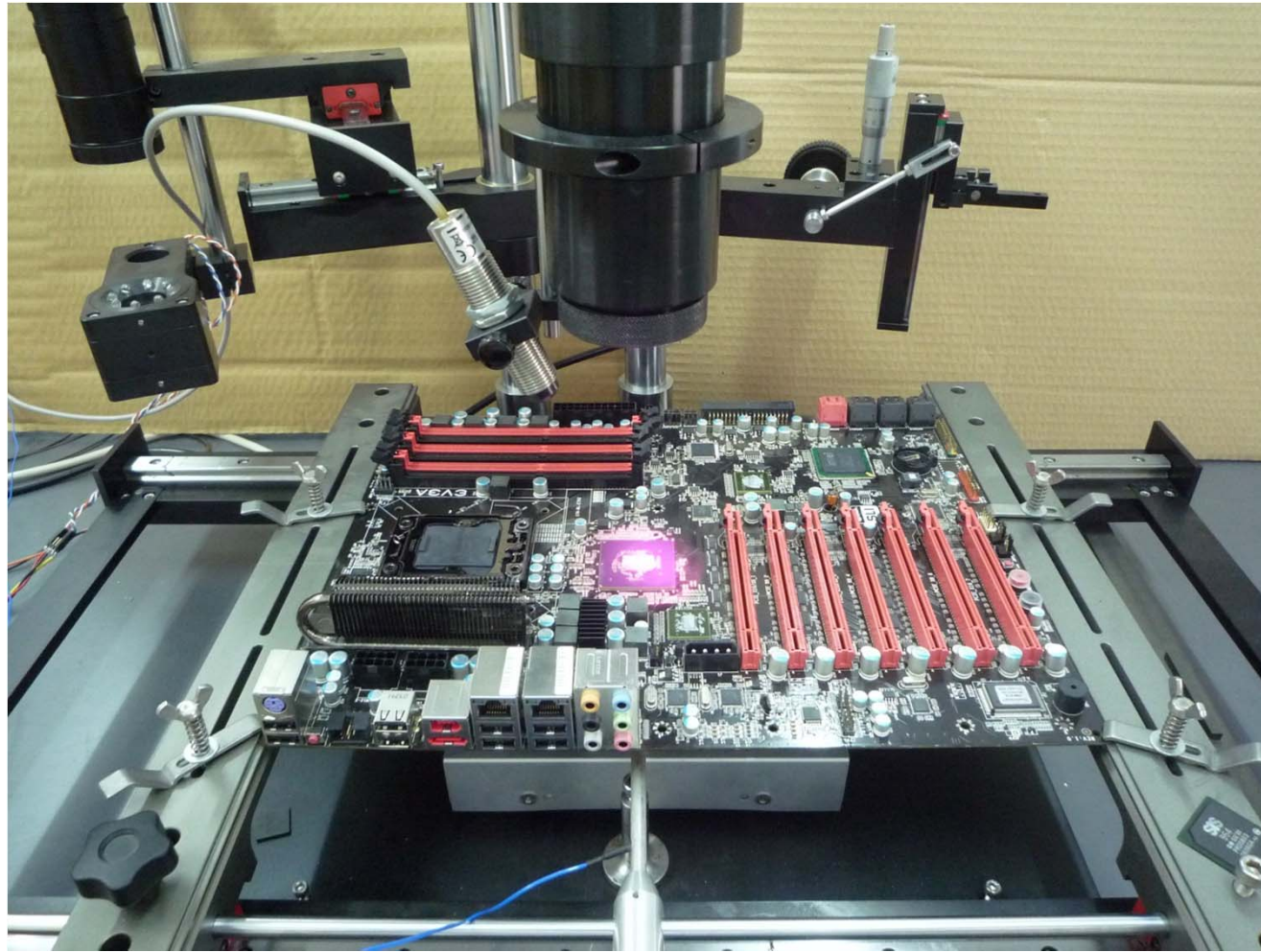


IR-600 advantage

- Non force heating, easy keep MB flat.
- Successful solder intel ich-10 chip on 230°C.
- IR heating, res. & cap. can not move parts.
- GUI interface, easy control and setting.
- Exact control top and bottom temperature.

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IR-600 view



GUI setting profile

Top Heater ■ ■ ■ ■ ■ ■ ■ ■

Bottom Heater ■ ■ ■ ■ ■ ■ ■ ■

Step	1	2	3	4	5	6	7
Type	PreHeat1	PreHeat2	Soak	ReFlow1	ReFlow2	ReFlow3	Keep
T/H - Max. Power (%)	60	60	60	60	60	60	50
Min. Power (%)	10	10	10	10	10	10	5
Limit (°C)	90	120	150	185	215	222	225
B/H - Max. Power (%)	60	70	70	70	70	60	50
Limit (°C)	80	100	135	170	205	215	220
Time (s)	45	45	50	50	50	50	40

Model: F無鉛-SB-SB

Starting Temp: 40

No. of Zone: 7

B/H Min. Power: 10 %

Cooling Start Time: 20 s

Cooling Ending Temp: 120 °C

Start Temp: 50 °C

Align Time(s): 30

Align Power (%): 20

LED: Off

5*5 Fan: Off

8*8 Fan: Off

Vacuum Pump: Off

Cooling Fan: Off

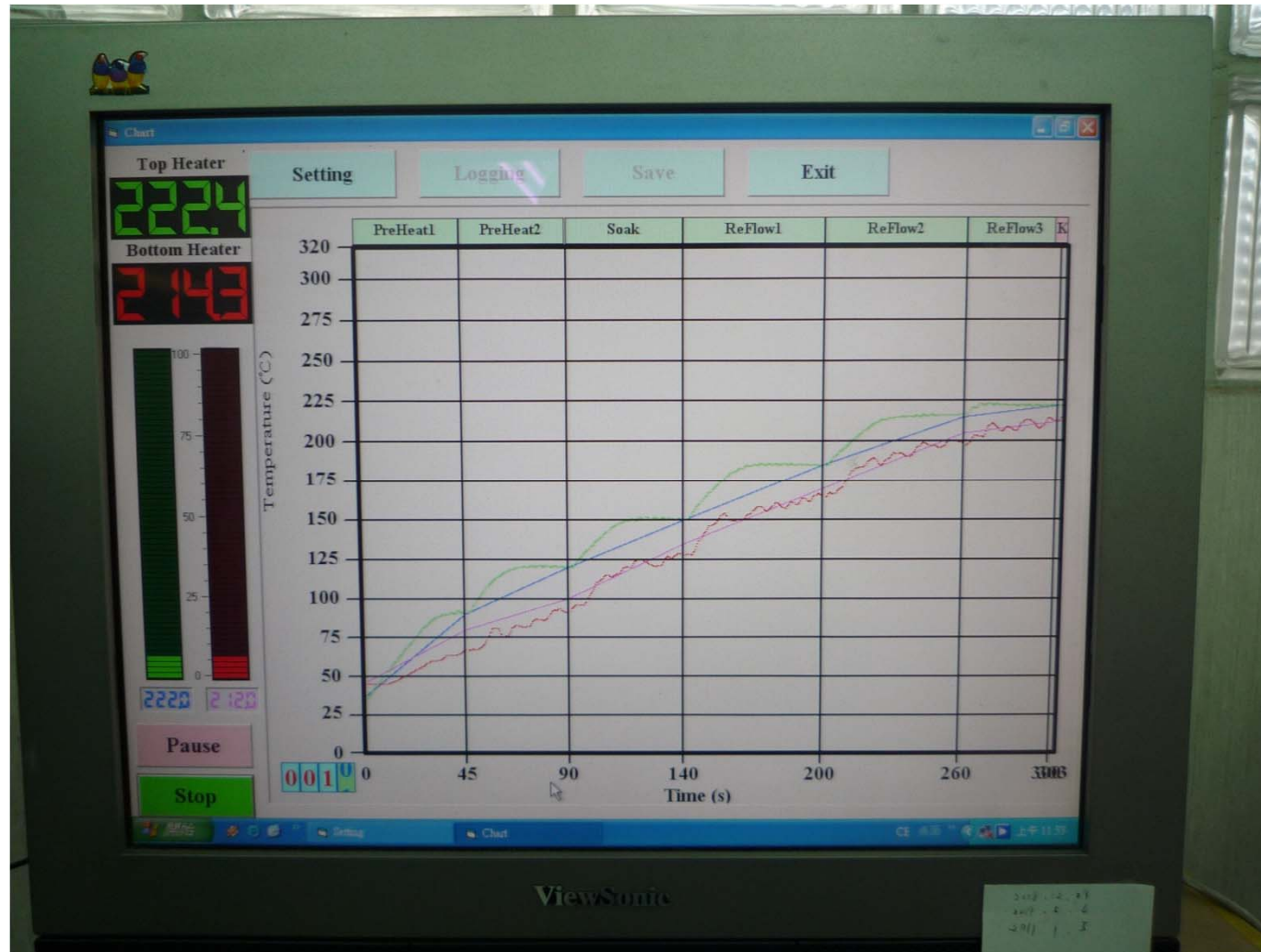
Bottom Heater 1: Off

Bottom Heater 2: Off

Heater 2 used

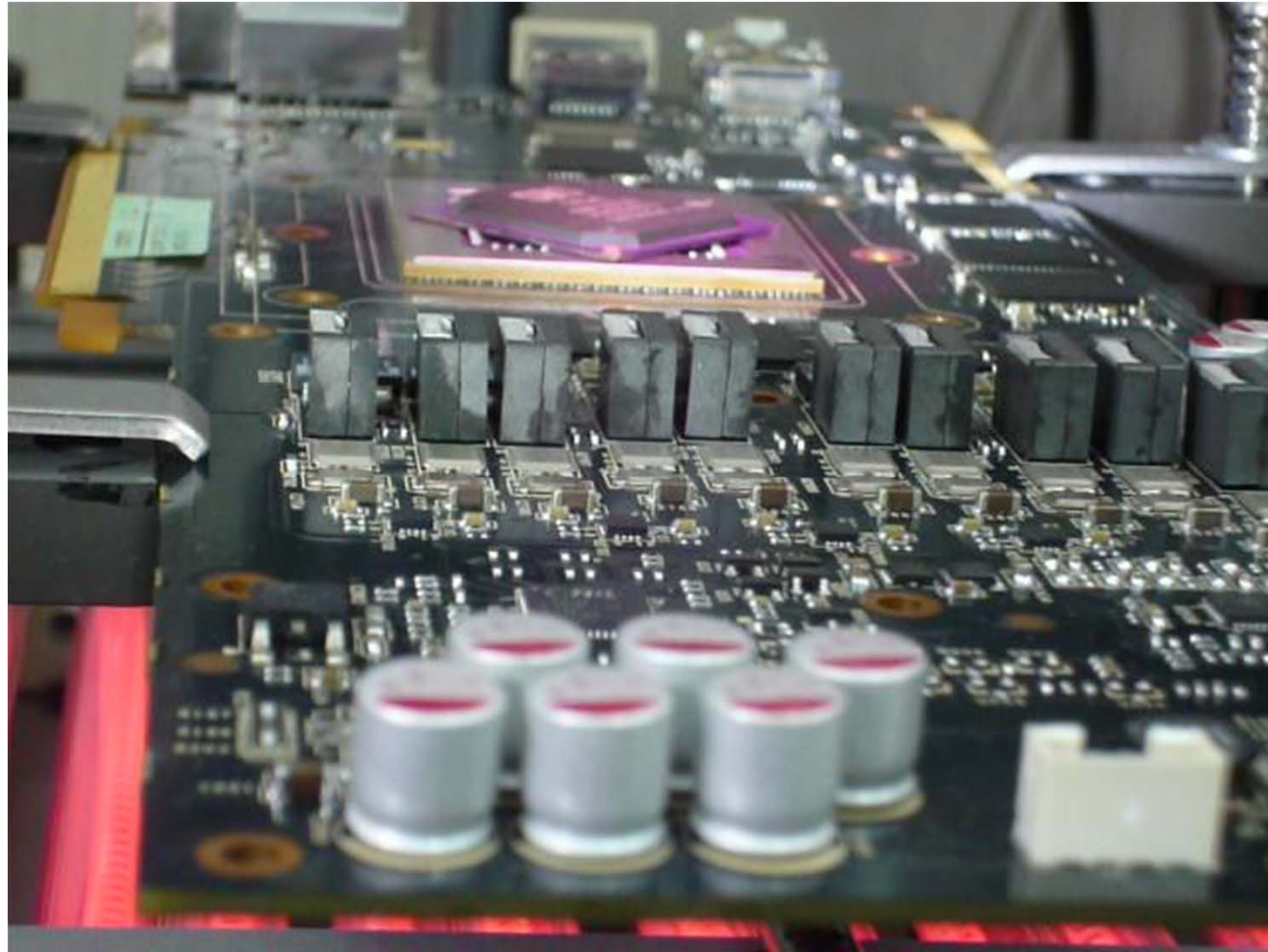
Buttons: Curves, Exit, Start, Save, Align Start

GUI profile



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Exact IR sensor

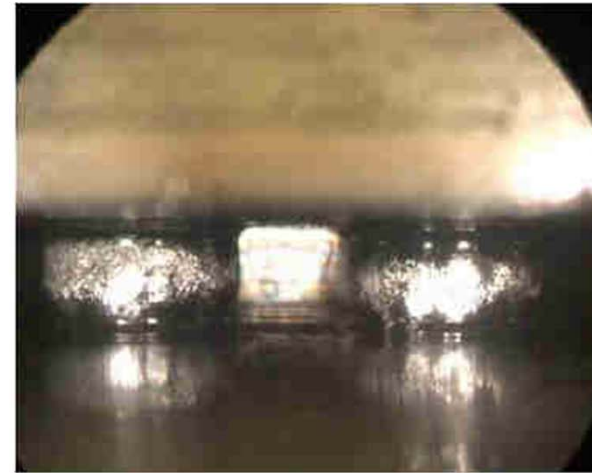


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X-Ray view the solder



只達一次融墜的錫點
..... 潛在風險



達到二次融墜的錫點
..... 好品質焊點

5 step in operating

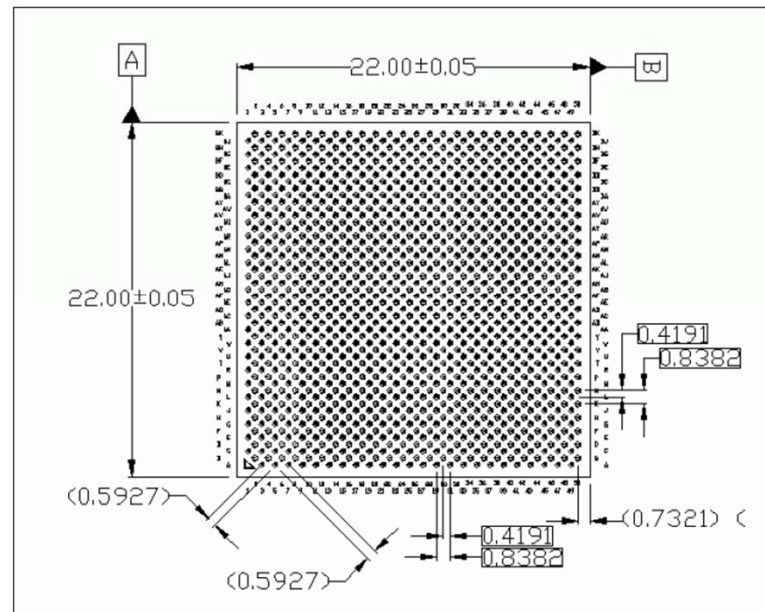
1. Fix MB.
2. Adjust position for top heating area.
3. Choice temp. profile.
4. Start.
5. Auto ending and auto cooling.

Successful solder ich10 on 230°C.

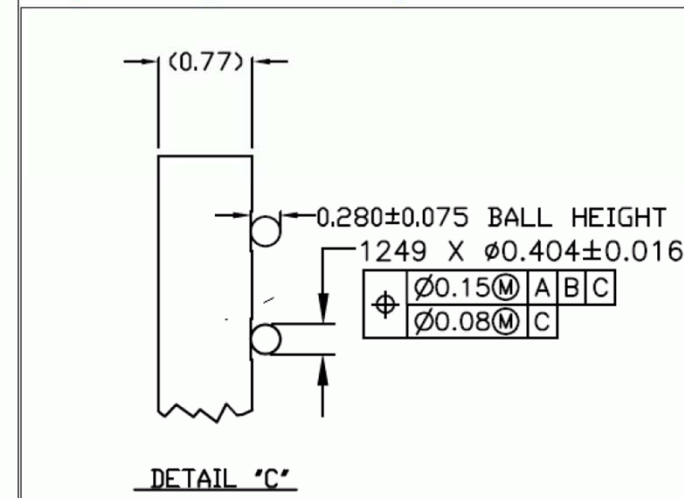
Case- table PC

- SCH ,AF82US15W,SLGFQ
- PAD pitch=0.419 , BALL size=0.404mm

Package Dimensions (Bottom View)

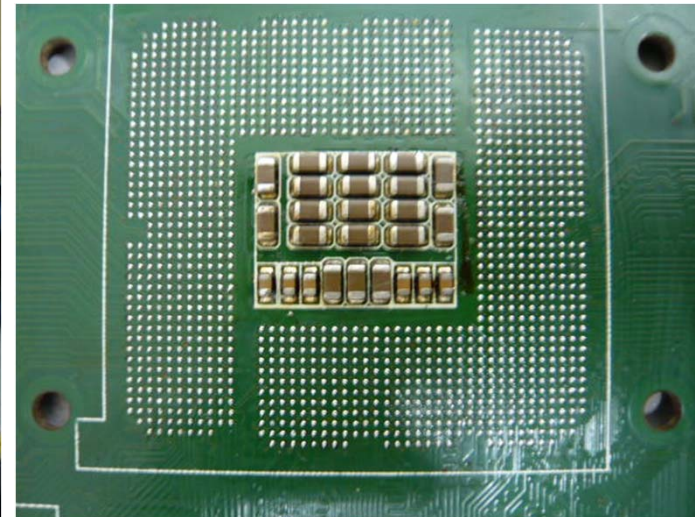
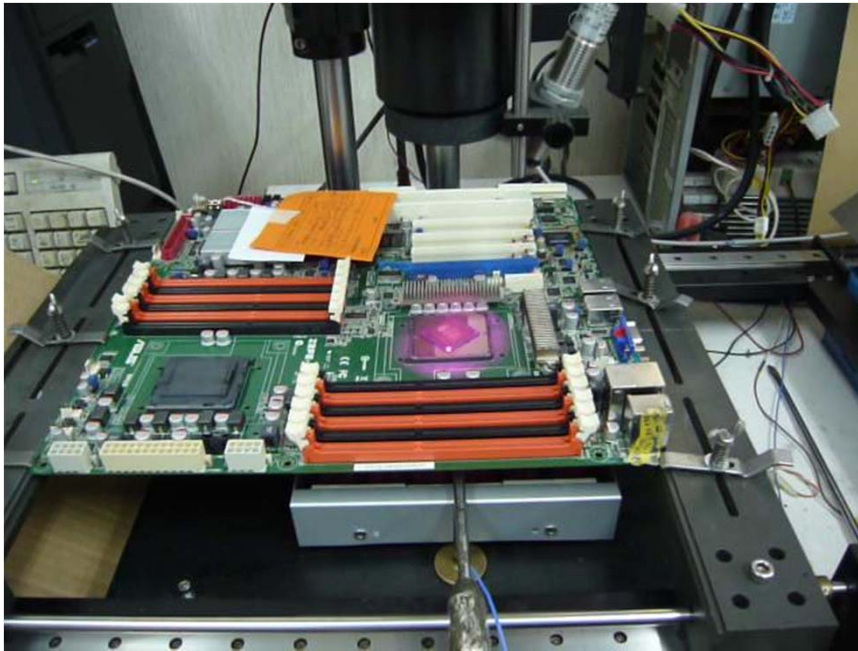


Package Dimensions (Solder Ball Detail "C")



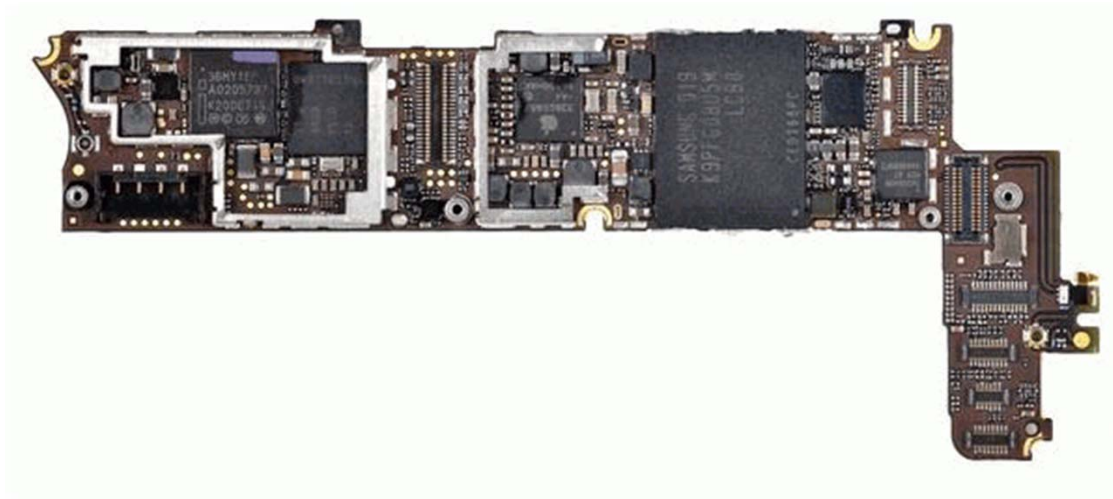
Case- server

- LGA1366 cpu socket
- SCH ,AF82US15W,SLGFQ
- PAD pitch=0.419 , BALL size=0.404mm



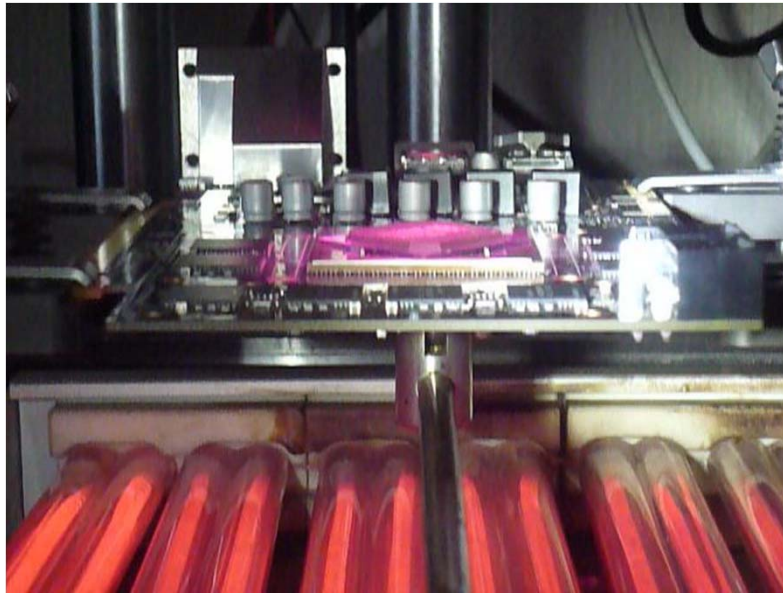
Case- mobile phone

- Non force heating, no moving the parts.



Case-GPU

- GPU NVIDIA GT6800
- Successful solder GPU on 230°C.



Conclusion

IR-600

over 95%+

successful solder

BGA chip.